

ABSTRACT

Provided are a sealing thermosetting-resin sheet and a hollow-package manufacturing method with or by each of which a material constituting a sealing thermosetting-resin sheet does not flow easily into a gap between an adherend and an electronic device. The invention relates to a sealing thermosetting-resin sheet used to manufacture a hollow package. About the sealing thermosetting-resin sheet, a cured body of this resin sheet has a sea-island structure. The structure includes a matrix part containing a first resin component as a main component, and a domain part containing a second resin component as a main component. The matrix part is softer than the domain part.